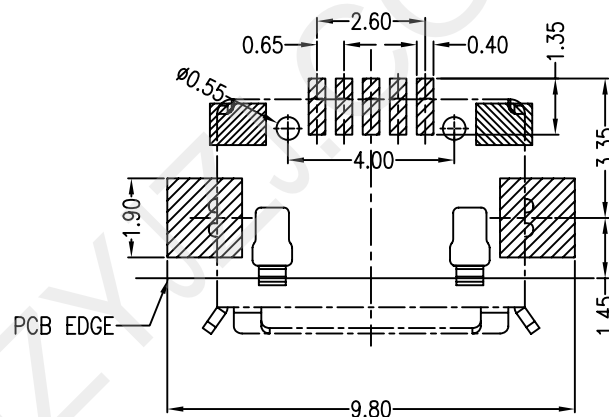
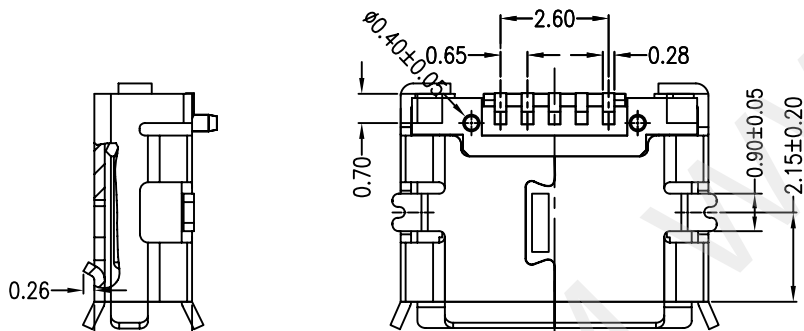
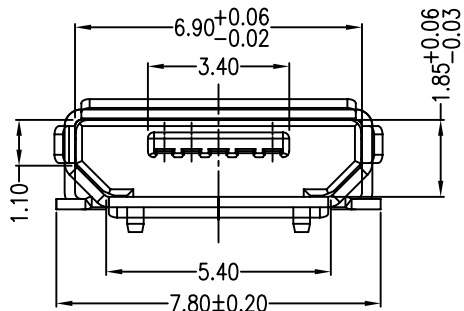
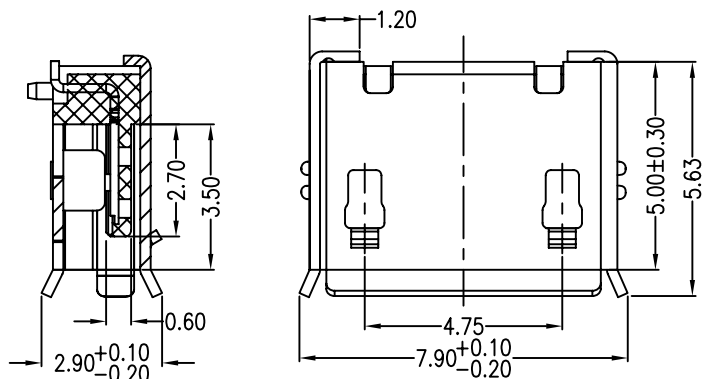
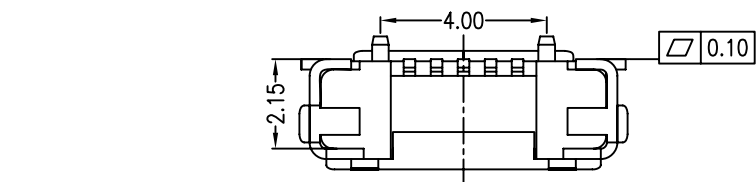




RECOMMENDED PCB LAYOUT

Note:

1.Material:

- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
- 1.2 Contact: copper alloy,t=0.20mm
- 1.3 Shell: copper alloy,t=0.25mm

2.Specification:

- 2.1 Current rating: 1 A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 50 mW Max.
- 2.4 Insulation resistance: 100 MW Min.
- 2.5 Total mating force: 3.57 Kg Max.
- 2.6 Total unmating force: 1.0 Kg Min.0.81~2.05 Kg Min.after 10000 insertion/extraction cycles
- 2.7 Temperature range: -30°C~80°C



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TOLERANCE:

x.x ±0.30
x.xx ±0.25
x.xxx ±0.15
x.' ±2" x.x' ±0.5"



UNIT: mm [inch]

SCALE:1:1 SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

MICRO USB 5P 全贴片加固有柱有边

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

HYC268-USB05-780

MOLD NO.

APPROVED BY:

邱敏

DATE :

2014-02-23

DRAW NO:

HYC-USB190529164

SHEET NO.

1 OF 1